

SN74ALVCH16901

18-BIT UNIVERSAL BUS TRANSCEIVER WITH PARITY GENERATORS/CHECKERS

SCES010F – JULY 1995 – REVISED SEPTEMBER 2004

- Member of the Texas Instruments Widebus™ Family
- UBT™ Transceiver Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode
- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 4.4 ns at 3.3 V
- ± 24 -mA Output Drive at 3.3 V
- Simultaneously Generates and Checks Parity
- Option to Select Generate Parity and Check or Feed-Through Data/Parity in A-to-B or B-to-A Directions
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

description/ordering information

This 18-bit (dual-octal) noninverting registered transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH16901 is a dual 9-bit to dual 9-bit parity transceiver with registers. The device can operate as a feed-through transceiver or it can generate/check parity from the two 8-bit data buses in either direction.

The SN74ALVCH16901 features independent clock (CLKAB or CLKBA), latch-enable (LEAB or LEBA), and dual 9-bit clock-enable ($\overline{\text{CLKENAB}}$ or $\overline{\text{CLKENBA}}$) inputs. It also provides parity-enable ($\overline{\text{SEL}}$) and parity-select (ODD/EVEN) inputs and separate error-signal ($\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$) outputs for checking parity. The direction of data flow is controlled by $\overline{\text{OEAB}}$ and $\overline{\text{OEBA}}$. When $\overline{\text{SEL}}$ is low, the parity functions are enabled. When $\overline{\text{SEL}}$ is high, the parity functions are disabled, and the device acts as an 18-bit registered transceiver.

DGG PACKAGE
(TOP VIEW)

$\overline{1\text{CLKENAB}}$	1	64	$\overline{1\text{CLKENBA}}$
LEAB	2	63	LEBA
CLKAB	3	62	CLKBA
$\overline{1\text{ERRA}}$	4	61	$\overline{1\text{ERRB}}$
$\overline{1\text{APAR}}$	5	60	$\overline{1\text{BPAR}}$
GND	6	59	GND
1A1	7	58	1B1
1A2	8	57	1B2
1A3	9	56	1B3
V_{CC}	10	55	V_{CC}
1A4	11	54	1B4
1A5	12	53	1B5
1A6	13	52	1B6
GND	14	51	GND
1A7	15	50	1B7
1A8	16	49	1B8
2A1	17	48	2B1
2A2	18	47	2B2
GND	19	46	GND
2A3	20	45	2B3
2A4	21	44	2B4
2A5	22	43	2B5
V_{CC}	23	42	V_{CC}
2A6	24	41	2B6
2A7	25	40	2B7
2A8	26	39	2B8
GND	27	38	GND
$\overline{2\text{APAR}}$	28	37	$\overline{2\text{BPAR}}$
$\overline{2\text{ERRA}}$	29	36	$\overline{2\text{ERRB}}$
$\overline{\text{OEAB}}$	30	35	$\overline{\text{OEBA}}$
$\overline{\text{SEL}}$	31	34	ODD/EVEN
$\overline{2\text{CLKENAB}}$	32	33	$\overline{2\text{CLKENBA}}$

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	TSSOP – DGG	Tape and reel	SN74ALVCH16901DGGR	ALVCH16901

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus and UBT are trademarks of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2004, Texas Instruments Incorporated

SN74ALVCH16901

18-BIT UNIVERSAL BUS TRANSCEIVER

WITH PARITY GENERATORS/CHECKERS

SCES010F – JULY 1995 – REVISED SEPTEMBER 2004

description/ordering information (continued)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The A and B I/Os and APAR and BPAR inputs have bus-hold circuitry. Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

Function Tables

FUNCTION†					
INPUTS					OUTPUT B
$\overline{CLKENAB}$	\overline{OEAB}	LEAB	CLKAB	A	
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	B_0^\ddagger
L	L	L	\uparrow	L	L
L	L	L	\uparrow	H	H
L	L	L	L	X	B_0^\ddagger
L	L	L	H	X	B_0^\S

† A-to-B data flow is shown; B-to-A flow is similar, but uses \overline{OEBA} , LEBA, and $\overline{CLKENBA}$.

‡ Output level before the indicated steady-state input conditions were established

§ Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

INPUTS			OPERATION OR FUNCTION
\overline{SEL}	\overline{OEBA}	\overline{OEAB}	
L	H	L	Parity is checked on port A and is generated on port B.
L	L	H	Parity is checked on port B and is generated on port A.
L	H	H	Parity is checked on port B and port A.
L	L	L	Parity is generated on port A and B if device is in FF mode.
H	L	L	Parity functions are disabled; device acts as a standard 18-bit registered transceiver.
H	L	H	
H	H	L	
H	H	H	

Q_A data to B, Q_B data to A
 Q_B data to A
 Q_A data to B
 Isolation

Function Tables (Continued)

PARITY											
INPUTS								OUTPUTS			
$\overline{\text{SEL}}$	$\overline{\text{OEBA}}$	$\overline{\text{OEAB}}$	ODD/ $\overline{\text{EVEN}}$	Σ OF INPUTS A1–A8 = H	Σ OF INPUTS B1–B8 = H	APAR	BPAR	APAR	$\overline{\text{ERRA}}$	BPAR	$\overline{\text{ERRB}}$
L	H	L	L	0, 2, 4, 6, 8	N/A	L	N/A	N/A	H	L	Z
L	H	L	L	1, 3, 5, 7	N/A	L	N/A	N/A	L	H	Z
L	H	L	L	0, 2, 4, 6, 8	N/A	H	N/A	N/A	L	L	Z
L	H	L	L	1, 3, 5, 7	N/A	H	N/A	N/A	H	H	Z
L	L	H	L	N/A	0, 2, 4, 6, 8	N/A	L	L	Z	N/A	H
L	L	H	L	N/A	1, 3, 5, 7	N/A	L	H	Z	N/A	L
L	L	H	L	N/A	0, 2, 4, 6, 8	N/A	H	L	Z	N/A	L
L	L	H	L	N/A	1, 3, 5, 7	N/A	H	H	Z	N/A	H
L	H	L	H	0, 2, 4, 6, 8	N/A	L	N/A	N/A	L	H	Z
L	H	L	H	1, 3, 5, 7	N/A	L	N/A	N/A	H	L	Z
L	H	L	H	0, 2, 4, 6, 8	N/A	H	N/A	N/A	H	H	Z
L	H	L	H	1, 3, 5, 7	N/A	H	N/A	N/A	L	L	Z
L	L	H	H	N/A	0, 2, 4, 6, 8	N/A	L	H	Z	N/A	L
L	L	H	H	N/A	1, 3, 5, 7	N/A	L	L	Z	N/A	H
L	L	H	H	N/A	0, 2, 4, 6, 8	N/A	H	H	Z	N/A	H
L	L	H	H	N/A	1, 3, 5, 7	N/A	H	H	L	Z	L
L	H	H	L	0, 2, 4, 6, 8	0, 2, 4, 6, 8	L	L	Z	H	Z	H
L	H	H	L	1, 3, 5, 7	1, 3, 5, 7	L	L	Z	L	Z	L
L	H	H	L	0, 2, 4, 6, 8	0, 2, 4, 6, 8	H	H	Z	L	Z	L
L	H	H	L	1, 3, 5, 7	1, 3, 5, 7	H	H	Z	H	Z	H
L	H	H	H	0, 2, 4, 6, 8	0, 2, 4, 6, 8	L	L	Z	L	Z	L
L	H	H	H	1, 3, 5, 7	1, 3, 5, 7	L	L	Z	H	Z	H
L	H	H	H	0, 2, 4, 6, 8	0, 2, 4, 6, 8	H	H	Z	H	Z	H
L	H	H	H	1, 3, 5, 7	1, 3, 5, 7	H	H	Z	L	Z	L
L	L	L	L	N/A	N/A	N/A	N/A	PE [†]	Z	PE [†]	Z
L	L	L	H	N/A	N/A	N/A	N/A	PO [‡]	Z	PO [‡]	Z

[†] Parity output is set to the level so that the specific bus side is set to even parity.

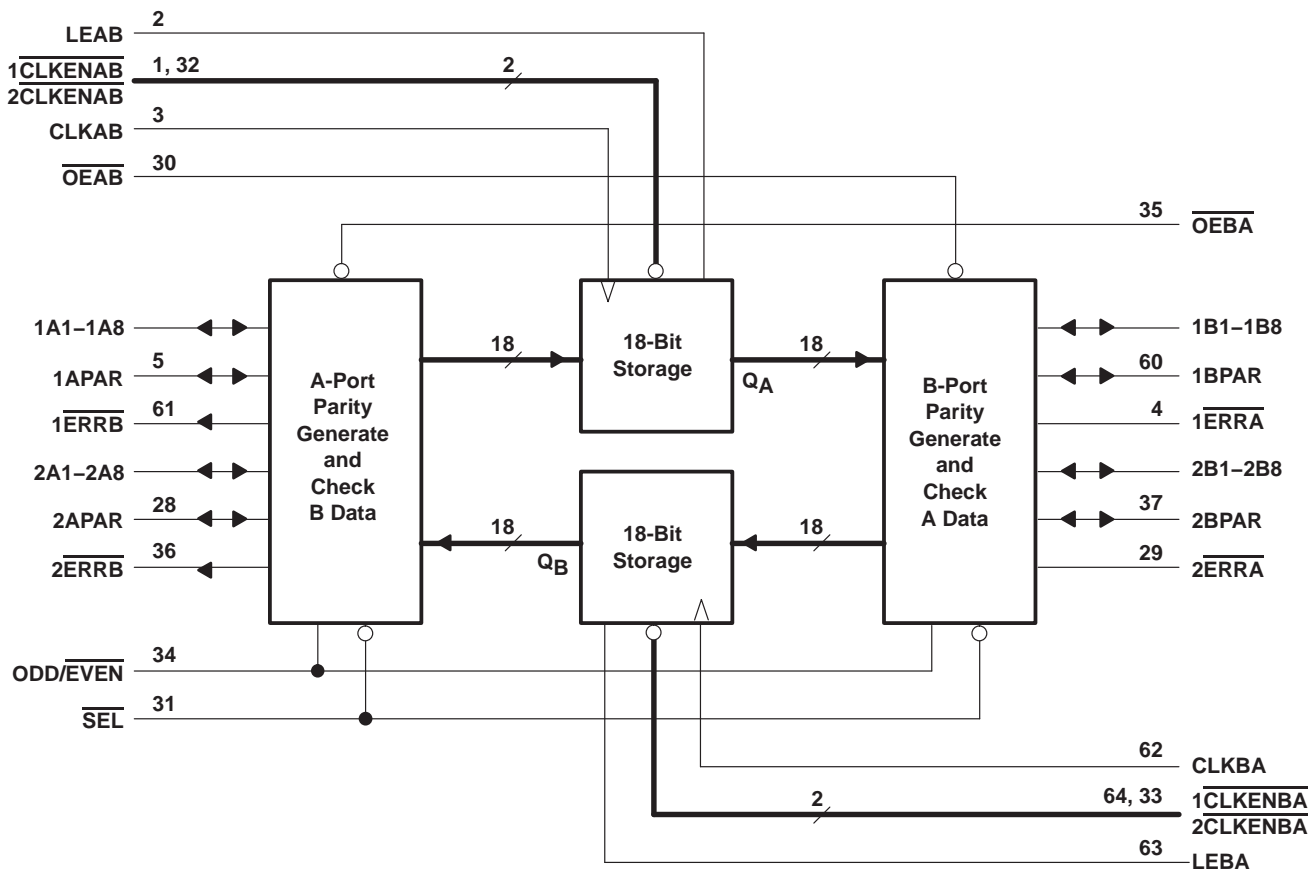
[‡] Parity output is set to the level so that the specific bus side is set to odd parity.

SN74ALVCH16901

18-BIT UNIVERSAL BUS TRANSCEIVER WITH PARITY GENERATORS/CHECKERS

SCES010F – JULY 1995 – REVISED SEPTEMBER 2004

functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I : Except I/O ports (see Note 1)	–0.5 V to 4.6 V
I/O ports (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Continuous output current, I_O	±50 mA
Continuous current through each V_{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3)	55°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. This value is limited to 4.6 V maximum.
3. The package thermal impedance is calculated in accordance with JESD 51–7.

SN74ALVCH16901
18-BIT UNIVERSAL BUS TRANSCEIVER
WITH PARITY GENERATORS/CHECKERS
 SCES010F – JULY 1995 – REVISED SEPTEMBER 2004

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V _{CC}	Supply voltage		1.65	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	1.7		
		V _{CC} = 2.7 V to 3.6 V	2		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	0.7		
		V _{CC} = 2.7 V to 3.6 V	0.8		
V _I	Input voltage		0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65 V	−4		mA
		V _{CC} = 2.3 V	−12		
		V _{CC} = 2.7 V	−12		
		V _{CC} = 3 V	−24		
I _{OL}	Low-level output current	V _{CC} = 1.65 V	4		mA
		V _{CC} = 2.3 V	12		
		V _{CC} = 2.7 V	12		
		V _{CC} = 3 V	24		
Δt/Δv	Input transition rise or fall rate			10	ns/V
T _A	Operating free-air temperature		−40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74ALVCH16901

18-BIT UNIVERSAL BUS TRANSCEIVER WITH PARITY GENERATORS/CHECKERS

SCES010F – JULY 1995 – REVISED SEPTEMBER 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP†	MAX	UNIT
V _{OH}		I _{OH} = –100 μA	1.65 V to 3.6 V	V _{CC} – 0.2			V
		I _{OH} = –4 mA	1.65 V	1.2			
		I _{OH} = –6 mA	2.3 V	2			
	I _{OH} = –12 mA		2.3 V	1.7			
			2.7 V	2.2			
			3 V	2.4			
		I _{OH} = –24 mA	3 V	2			
V _{OL}		I _{OL} = 100 μA	1.65 V to 3.6 V	0.2			V
		I _{OL} = 4 mA	1.65 V	0.45			
		I _{OL} = 6 mA	2.3 V	0.4			
	I _{OL} = 12 mA		2.3 V	0.7			
			2.7 V	0.4			
		I _{OL} = 24 mA	3 V	0.55			
I _I		V _I = V _{CC} or GND	3.6 V	±5		μA	
I _I (hold)		V _I = 0.58 V	1.65 V	25			μA
		V _I = 1.07 V	1.65 V	–25			
		V _I = 0.7 V	2.3 V	45			
		V _I = 1.7 V	2.3 V	–45			
		V _I = 0.8 V	3 V	75			
		V _I = 2 V	3 V	–75			
		V _I = 0 to 3.6 V‡	3.6 V	±500			
I _{OZ} §		V _O = V _{CC} or GND	3.6 V	±10		μA	
I _{CC}		V _I = V _{CC} or GND, I _O = 0	3.6 V	40		μA	
ΔI _{CC}		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V	750		μA	
C _i	Control inputs	V _I = V _{CC} or GND	3.3 V	3		pF	
C _{io}	A or B ports	V _O = V _{CC} or GND	3.3 V	7.5		pF	
C _o	$\overline{\text{ERR}}$ ports	V _O = V _{CC} or GND	3.3 V	6		pF	

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			†		125		125		125	MHz
t_w	Pulse duration	CLK↑		†		3		3		3	ns
		LE high		†		3		3		3	
t_{su}	Setup time	A, APAR or B, BPAR before CLK↑		†		1.9		2		1.7	ns
		CLKEN before CLK↑		†		2.1		2.1		1.7	
		A, APAR or B, BPAR before LE↓		†		1.4		1.3		1.2	
t_h	Hold time	A, APAR or B, BPAR after CLK↑		†		0.4		0.4		0.5	ns
		CLKEN after CLK↑		†		0.5		0.5		0.7	
		A, APAR or B, BPAR after LE↓		†		0.9		1.1		0.9	

† This information was not available at the time of publication.

SN74ALVCH16901

18-BIT UNIVERSAL BUS TRANSCEIVER WITH PARITY GENERATORS/CHECKERS

SCES010F – JULY 1995 – REVISED SEPTEMBER 2004

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			†		125		125		125		MHz
t _{pd}	A or B	B or A		†	1	5.2		4.8	1	4.4	ns
		BPAR or APAR		†	2	8.9		7.6	2	6.7	
	APAR or BPAR	BPAR or APAR		†	1	5.7		5.2	1	4.7	
		ERRA or ERRB		†	2	9.7		8.7	2	7.5	
	ODD/EVEN	ERRA or ERRB		†	1.5	8.7		7.9	1.5	6.8	
		BPAR or APAR		†	1.5	8.3		7.6	1.5	6.5	
	SEL	BPAR or APAR		†	1	6.1		5.9	1	5.1	
	CLKAB or CLKBA	A or B		†	1	6.4		5.8	1	5.1	
		BPAR or APAR parity feed through		†	1.5	7.1		6.3	1.5	5.6	
		BPAR or APAR parity generated		†	2.5	10.2		8.7	2	7.7	
		ERRA or ERRB		†	2.5	10.5		8.9	2	7.9	
	LEAB or LEBA	A or B		†	1	6		5.5	1	4.8	
		BPAR or APAR parity feed through		†	1.5	6.7		6	1.5	5.3	
		BPAR or APAR parity generated		†	2.5	9.8		8.3	2	7.4	
		ERRA or ERRB		†	2.5	9.9		8.5	2	7.5	
t _{en}	OEAB or OEBA	B, BPAR or A, APAR		†	1.4	6.3		6.1	1	5.3	ns
t _{dis}	OEAB or OEBA	B, BPAR or A, APAR		†	1.3	6.1		5.2	1.5	4.9	ns
t _{en}	OEAB or OEBA	ERRA or ERRB		†	1.4	6.2		5.5	1	4.9	ns
t _{dis}	OEAB or OEBA	ERRA or ERRB		†	1.3	7.3		6.5	1	5.7	ns
t _{en}	SEL	ERRA or ERRB		†	1.4	6.7		6.5	1	5.5	ns
t _{dis}	SEL	ERRA or ERRB		†	1.3	6.4		5.4	1.5	4.9	ns

† This information was not available at the time of publication.

operating characteristics, T_A = 25°C

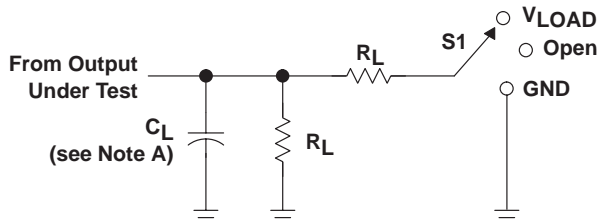
PARAMETER			TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT
				TYP	TYP	TYP	
C _{pd}	Power dissipation capacitance	Outputs enabled	C _L = 50 pF, f = 10 MHz	†	22	27	pF
		Outputs disabled		†	5	8	

† This information was not available at the time of publication.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

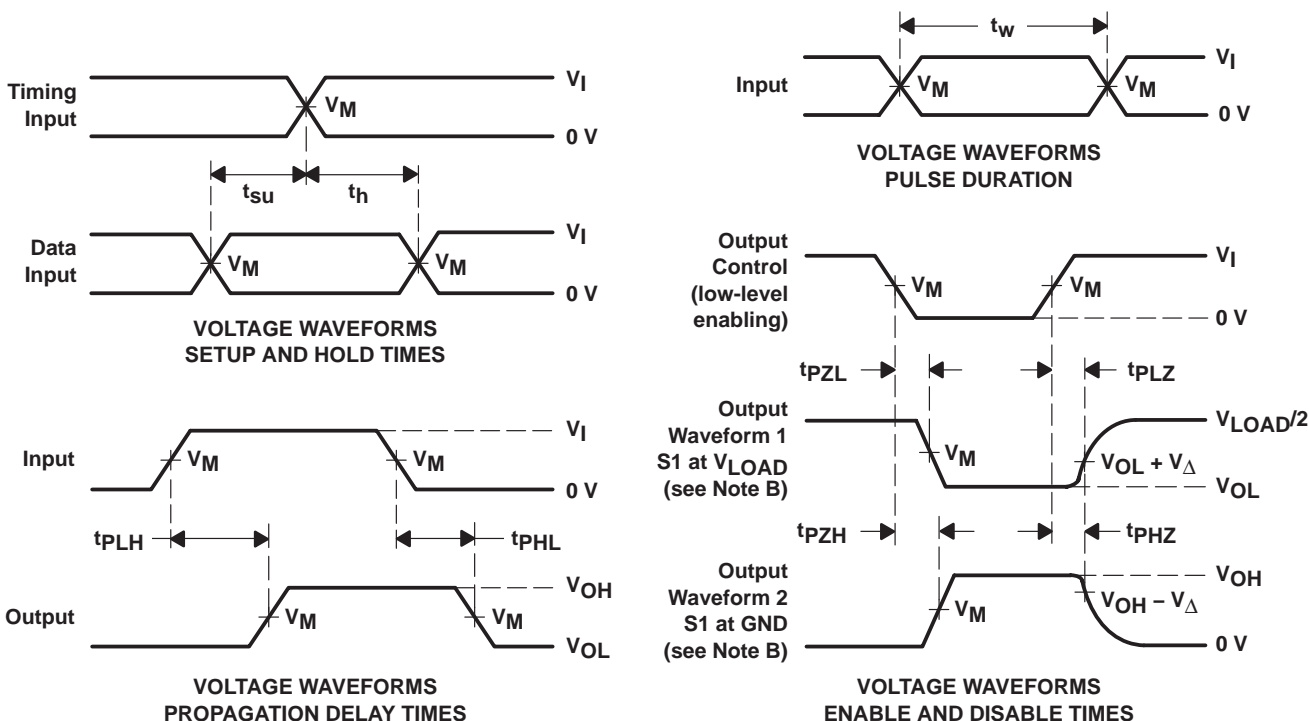
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open V_{LOAD} GND

V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
1.8 V	V_{CC}	≤ 2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	V_{CC}	≤ 2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3 \text{ V} \pm 0.3 \text{ V}$	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVCH16901DGGRE4	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16901DGGRG4	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16901DGGGR	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH16901DGGR	TSSOP	DGG	64	2000	330.0	24.4	8.4	17.3	1.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH16901DGGR	TSSOP	DGG	64	2000	346.0	346.0	41.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2008, Texas Instruments Incorporated